ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi					rials and M	ials and Mfg Information			
upplier Inform	ation														
Company name*			Company unique ID			ι	Unique ID Authority					Response Date*			
onsemi											2024-04	2024-04-25			
Contact Name		Title	Title - Contact			F	Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewa	rds	Prod	Product Enviro Compliance			1	NA				Produ	Product-Env-Stewards@onsemi.com			
uthorized Represe	ntative*	Title	Title - Representative			F	Phone - Representative*				Email -	Email - Representative*			
Product-Env-Stewa	rds	Proc	Product Enviro Compliance]	NA				Produ	Product-Env-Stewards@onsemi.com			
Requeste	r Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Versio	on :	Manufacturing Site		Weight*	UOM	Unit Type	
		NCP163AFCS	ICP163AFCS180T2G CSP LDO 250 mA, UI High PSRR, Active Di		, Ultra-Low Noi e Discharge	se and	2024-04-25			CNQ		0.34614	mg	Each	
Ianufacturing l	Proccess Information	on													
Terminal Plating / Grid Array Material			Ferminal Base Alloy J-STD-020 MSI		STD-020 MSL	Rating	Peak Process Body Temperature Max Time at Pea			k Temperature Number of Reflow Cycles					
SnAgCu			CU Alloy 1				260	C 30		seco	nds 3				
omments															
vel 1 - maximum ti	ime at peak temperature	during solderin	ng is 10-30	seconds	·	·			·	·		·	·	·	
or more informatio	on regarding material co	mposition please	se refer to p	page 3										·	

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.2396	mg	Supplier	Silicon (Si)	7440-21-3		0.2396	mg
Protection coat	0.0089	mg		Polyimide	proprietary data		0.0089	mg
Solder Ball	0.0903	mg	Supplier	Silver (Ag)	7440-22-4		0.0023	mg
			Supplier	Tin (Sn)	7440-31-5		0.0874	mg
			Supplier	Copper (Cu)	7440-50-8		0.0005	mg
UBM Sputter	4.4E-4	mg	Supplier	Titanium (Ti)	7440-32-6		0	mg
			Supplier	Copper (Cu)	7440-50-8		0.0004	mg
Under Bump Metal	0.0069	mg	Supplier	Copper (Cu)	7440-50-8		0.0069	mg